

ABSTRACT OF THE DISCLOSURE

According to the package and the method for manufacturing the package of the present invention, a chip can be formed extremely to be thin, and manufactured at lower cost and higher throughput, and the variations of a chip thickness can be reduced without back grind that causes cracks or polishing marks. In the present invention, a semiconductor film with a thickness of at most 500 μm deposited over a substrate serving as a support medium is crystallized with a CW laser light, and a chip having a semiconductor device is formed to have a total thickness of 5 μm , preferably at most 2 μm by using the crystallized semiconductor film.

Consequently, the chip is mounted on an interposer after separating a substrate.